



Lead-Free Wave and Dip Solder Pot Suggested Maximum Levels

Contaminant element	SAC Alloys % by weight	SN100C Alloy % by weight
Ag (Silver)	4.25	0.5
Au (Gold)	0.8	0.8
Al (Aluminum)	0.006	0.006
Bi (Bismuth)	0.1	0.1
Cu (Copper)	1.2	1.2
Fe (Iron)	0.04	0.04
Ni (Nickel)	0.05	0.08
Pb (Lead)	0.1	0.1
Sb (Antimony)	0.2	0.2
Zn (Zinc)	0.006	0.006

Action to Take if Exceeding Dump Limits

Frequent pot analysis is the best deterrent to solder pot contamination. AIM recommends that you keep records of frequent analyses to monitor the increase in contaminants.

If none of the major elements in the alloy increases, you may dilute the solder pot with the same type of alloy to reduce the contaminant level.

If one of the major elements in the alloy does increase, you should dilute the solder pot with the recommended top-off alloy. For example, if a SAC alloy increases in copper, you should dilute the solder pot with tin or tin-silver. If SN100C increases in copper, you should top off the pot with SN100Ce.

Dilution is the first option and best choice for contaminant reduction. If dilution using a top-off alloy is not successful, then a partial drain of the pot may be necessary to reduce the contaminant level.

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